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High voltage fast-switching NPN power transistor

Features

- High voltage capability
- Low spread of dynamic parameters
- Minimum lot-to-lot spread for reliable operation
- Very high switching speed

Applications

- Electronic ballast for fluorescent lighting
- Electronic transformer for halogen lamps

Description

The device is manufactured using high voltage Multi Epitaxial Planar technology for high switching speeds. It uses a cellular emitter structure with planar edge termination to enhance switching speeds while maintaining a satisfactory RBSOA.

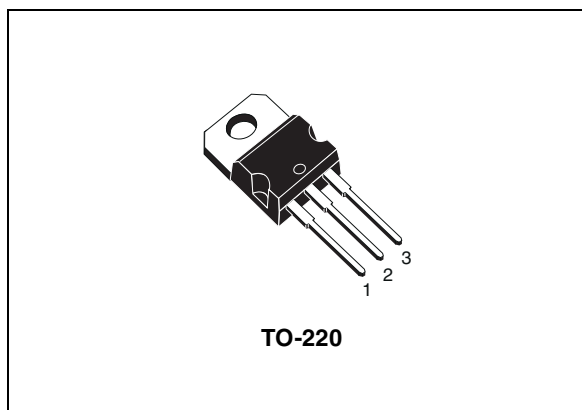


Figure 1. Internal schematic diagrams

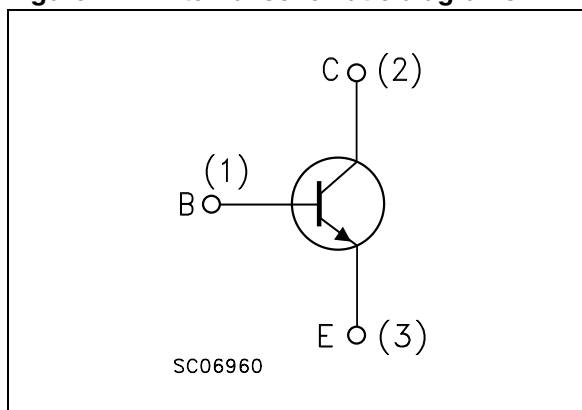


Table 1. Device summary

Order code	Marking	Package	Packaging
TR136	TR136	TO-220	Tube

1 Electrical ratings

Table 2. Absolute maximum rating

Symbol	Parameter	Value	Unit
V_{CES}	Collector-emitter voltage ($V_{BE} = 0$)	700	V
V_{CEO}	Collector-emitter voltage ($I_B = 0$)	400	V
V_{EBO}	Emitter-base voltage ($I_C = 0$)	9	V
I_C	Collector current	3	A
I_{CM}	Collector peak current ($t_P < 5\text{ms}$)	6	A
I_B	Base current	1.5	A
I_{BM}	Base peak current ($t_P < 5\text{ms}$)	3	A
P_{tot}	Total dissipation at $T_c \leq 25^\circ\text{C}$	60	W
T_{stg}	Storage temperature	-65 to 150	$^\circ\text{C}$
T_J	Max. operating junction temperature	150	$^\circ\text{C}$

2 Electrical characteristics

($T_{\text{case}} = 25^{\circ}\text{C}$ unless otherwise specified)

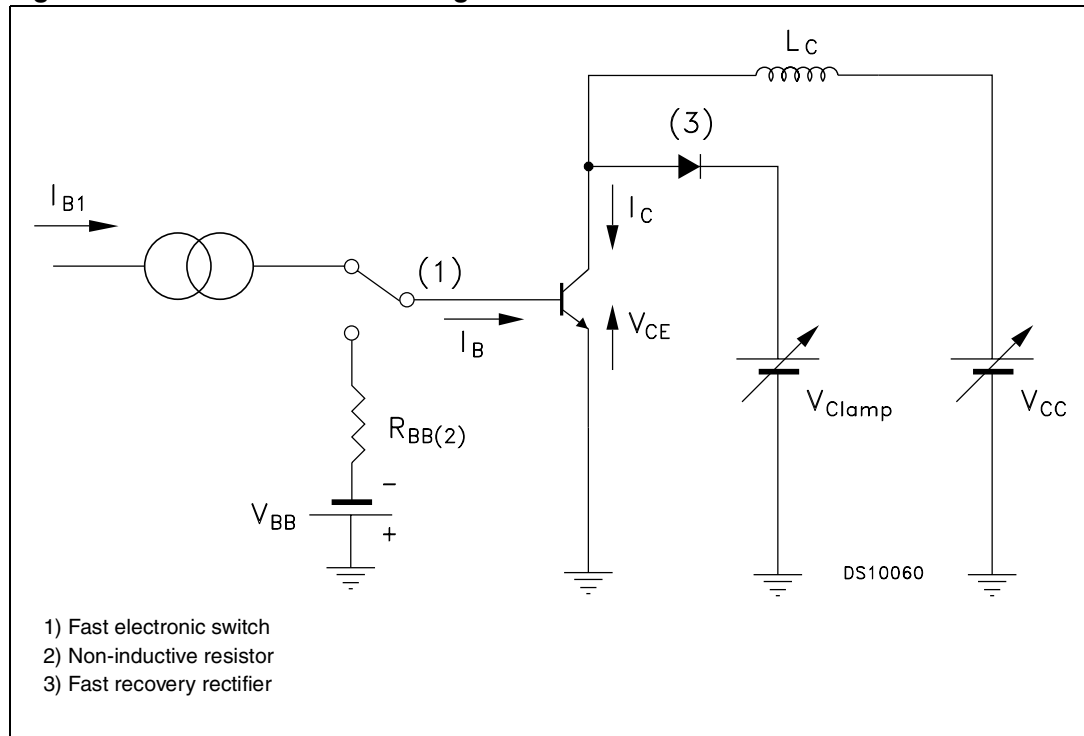
Table 3. Electrical characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{CEV}	Collector cut-off current ($V_{\text{BE}} = -1.5\text{V}$)	$V_{\text{CE}} = 700\text{ V}$			1	mA
		$V_{\text{CE}} = 700\text{ V}$ $T_{\text{C}} = 100^{\circ}\text{C}$			5	mA
I_{EBO}	Emitter cut-off current ($I_{\text{C}} = 0$)	$V_{\text{EB}} = 9\text{ V}$			1	mA
$V_{\text{CEO(sus)}}^{(1)}$	Collector-emitter sustaining voltage ($I_{\text{B}} = 0$)	$I_{\text{C}} = 10\text{ mA}$	400			V
$V_{\text{CE(sat)}}^{(1)}$	Collector-emitter saturation voltage	$I_{\text{C}} = 0.5\text{ A}$ $I_{\text{B}} = 0.1\text{ A}$			0.5	V
		$I_{\text{C}} = 0.6\text{ A}$ $I_{\text{B}} = 60\text{ mA}$			0.7	V
		$I_{\text{C}} = 2\text{ A}$ $I_{\text{B}} = 0.5\text{ A}$			1	V
$V_{\text{BE(sat)}}^{(1)}$	Base-emitter saturation voltage	$I_{\text{C}} = 1\text{ A}$ $I_{\text{B}} = 0.2\text{ A}$			1.2	V
		$I_{\text{C}} = 2\text{ A}$ $I_{\text{B}} = 0.5\text{ A}$			1.6	V
h_{FE}	DC current gain	$I_{\text{C}} = 10\text{ mA}$ $V_{\text{CE}} = 5\text{ V}$	10			
		$I_{\text{C}} = 2\text{ A}$ $V_{\text{CE}} = 5\text{ V}$	10		20	
t_{s} t_{f}	Inductive load Storage time Fall time	$I_{\text{C}} = 1\text{ A}$ $R_{\text{BB}} = 0\ \Omega$		0.8		μs
		$V_{\text{Clamp}} = 200\text{ V}$ $L = 50\text{ mH}$ (see Figure 2)		0.16		μs

1. Pulsed duration = 300 ms, duty cycle $\leq 1.5\%$

2.1 Test circuits

Figure 2. Inductive load switching test circuit

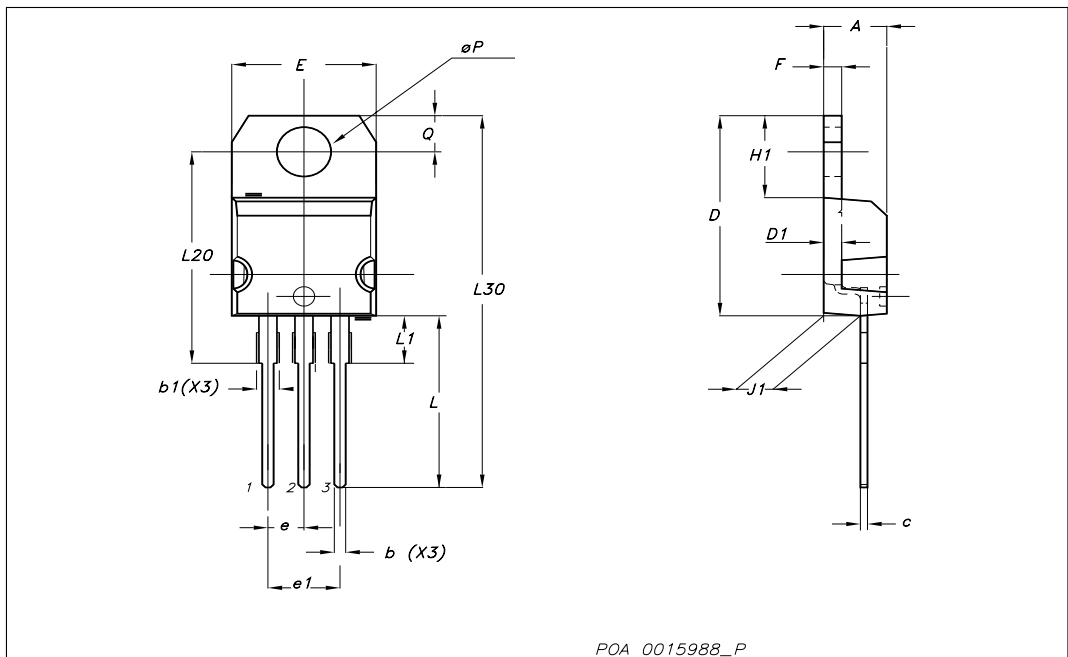


3 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

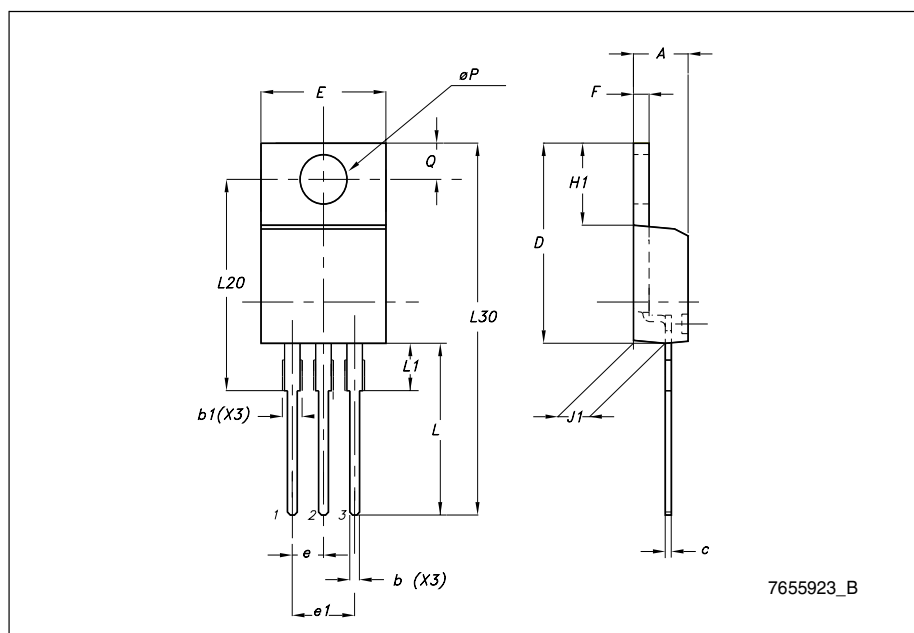
TO-220 mechanical data

Dim	mm			inch		
	Min	Typ	Max	Min	Typ	Max
A	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.14		1.70	0.044		0.066
c	0.49		0.70	0.019		0.027
D	15.25		15.75	0.6		0.62
D1		1.27			0.050	
E	10		10.40	0.393		0.409
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.051
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
∅P	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116



TO-220 type E mechanical data

DIM.	mm.		
	MIN.	TYP	MAX.
A	4.47		4.67
b	0.70		0.91
b1	1.17		1.37
c	0.31		0.53
D	14.60		15.70
E	9.96		10.36
e		2.54	
e1	4.98	5.08	5.18
F	1.17		1.37
H1	6.10		6.80
J1	2.52		2.82
L	12.70		13.80
L1	3.20		3.96
L20	15.21		16.77
ϕP	3.73		3.94
Q	2.59		2.89



4 Revision history

Table 4. Document revision history

Date	Revision	Changes
08-Oct-2007	1	Initial release
08-Feb-2008	2	Updated TO-220, type E, mechanical data

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